LINQSOL™ EMC-G194

Black epoxy molding compound

- Green molding compound
- Cost-effective molding compound with high adhesion and thermal stability
- Designed for rectifier diode, SMX, TO and DIP packages

LINQSOL™ EMC-G194 is a green epoxy molding compound engineered for use in rectifier diodes, SMX, TO, and DIP semiconductor packages. It is designed for efficient, high-volume molding operations with excellent flow and low internal stress. This makes it ideal for devices with complex shapes or tight process requirements. **EMC-G194** has high adhesion strength on leadframes, copper, and other common substrate materials, reducing delamination risks and ensuring mechanical stability during thermal cycling and high-temperature operation.

EMC-G194 delivers high performance and reliability while meeting EU RoHS requirements and REACH Substances of Very High Concern (SVHC) restrictions**.** Overall, **EMC-G194** seamlessly integrates advanced material properties, safety compliance, and superior performance for reliable semiconductor encapsulation.

Cured properties

Property	Value	Unit
General Properties		
Filler content	74	%
Filler shape	Fused	
Filler sieving size	150	µm
Specific gravity	1.82	–
Spiral flow *at 175°C*	74	cm
Chemical Properties		
Ion content Chloride (Cl^-) concentration Sodium (Na^+) concentration	 6 8	 ppm ppm
Water absorption *(PCT 24 h)*	0.44	%
pH of extract	5	–
Electrical conductivity of extract	100	$\mu S \cdot cm^{-1}$
Mechanical Properties		
Flexural strength	140	MPa
Flexural modulus	15	GPa

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Thermal Properties		
Glass transition temperature	175	°C
Coefficient of thermal expansion, α1	16	ppm/°C
Coefficient of thermal expansion, α2	62	ppm/°C
Gel time *at 175°C*	22	s
Thermal conductivity	0.7	W/mK
Flammability rating	V-0	UL-94

Recommended mold parameters

Parameter	Value	Unit
Molding temperature	170–180	°C
Transfer pressure	40–70	kg_f/cm^2
Transfer time	17–25	s
Cure time *at 175°C*	90–150	s
Post mold cure time *at 175°C*	6–8	h

The curing conditions provided are recommended guidelines based on typical laboratory results. Actual curing parameters should be defined and validated by the user to ensure compatibility with specific materials, part geometries, and end-use requirements. It is the user's responsibility to optimize and confirm curing conditions that meet their performance and quality standards.

Processing Instructions

- Before use, let **LINQSOL EMC-G194** reach room temperature (23±5 °C) for 24 hours. Keep the bag unopened and stored in a dry location with a relative humidity of ≤50% during thawing to prevent moisture contamination.
- Use the materials within 72 hours after removing the container from cold storage.

Storage and Handling

LINQSOL EMC-G194 is available in pressed pellets in a wide range of sizes to meet specific customer needs. To ensure product integrity, keep it away from oxidizing materials. For long-term storage, maintain a cold environment. The shelf life when stored below 5 °C is 183 days.

The technical information presented in this document is provided for reference only and does not constitute a guarantee of specific properties or performance. Actual results may vary depending on individual conditions and application methods. Users are strongly advised to perform their own testing and validation to determine suitability for their intended use and compliance with relevant regulations.

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